

## Automotive-grade dual N-channel 40 V, 8 mΩ typ., 15 A STripFET™ F5 Power MOSFET in a PowerFLAT™ 5x6 double island

Datasheet — production data

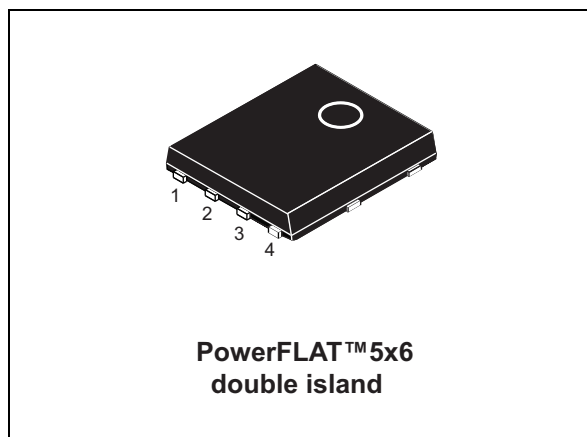
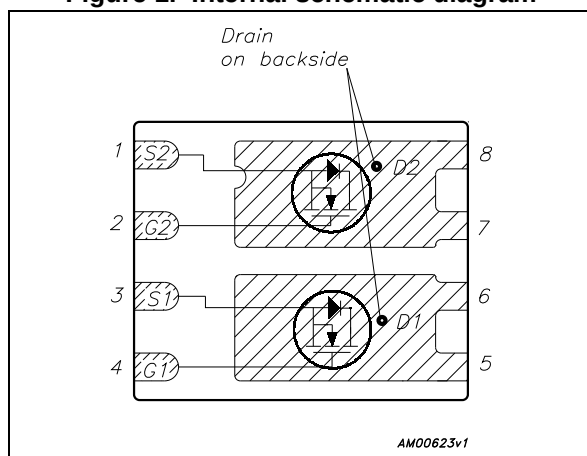


Figure 1. Internal schematic diagram



### Features

| Order code | V <sub>DS</sub> | R <sub>DS(on)</sub> max. | I <sub>D</sub> |
|------------|-----------------|--------------------------|----------------|
| STL15DN4F5 | 40 V            | 9 mΩ                     | 15 A           |

- Designed for automotive applications and AEC-Q101 qualified
- Extremely low on-resistance R<sub>DS(on)</sub>
- Very low gate charge
- Low gate drive power loss
- Wettable flank package option

### Applications

- Switching applications

### Description

This device is a dual N-channel Power MOSFET developed using STMicroelectronics' STripFET™ F5 technology. The device has been optimized to achieve very low on-state resistance, contributing to a FOM that is among the best in class.

Table 1. Device summary

| Order code | Marking | Packages <sup>(1)</sup>      | Packaging     |
|------------|---------|------------------------------|---------------|
| STL15DN4F5 | 15DN4F5 | PowerFLAT™ 5x6 double island | Tape and reel |

1. For wettable flank option, please contact ST sale offices.

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

| Symbol             | Parameter                                                                | Value      | Unit             |
|--------------------|--------------------------------------------------------------------------|------------|------------------|
| $V_{DS}$           | Drain-source voltage                                                     | 40         | V                |
| $V_{GS}$           | Gate-source voltage                                                      | $\pm 20$   | V                |
| $I_D^{(1)}$        | Drain current (continuous) at $T_C = 25^\circ\text{C}$ (silicon limited) | 60         | A                |
| $I_D^{(2)}$        | Drain current (continuous) at $T_{pcb} = 25^\circ\text{C}$               | 15         | A                |
| $I_D^{(2)}$        | Drain current (continuous) at $T_{pcb} = 100^\circ\text{C}$              | 10         | A                |
| $I_{DM}^{(2),(3)}$ | Drain current (pulsed)                                                   | 60         | A                |
| $P_{TOT}^{(1)}$    | Total dissipation at $T_C = 25^\circ\text{C}$                            | 60         | W                |
| $P_{TOT}^{(2)}$    | Total dissipation at $T_{pcb} = 25^\circ\text{C}$ , $t < 10$ sec         | 4.3        | W                |
| $T_J$<br>$T_{stg}$ | Operating junction temperature<br>Storage temperature                    | -55 to 175 | $^\circ\text{C}$ |

1. The value is rated according  $R_{thj-c}$
2. The value is rated according  $R_{thj-pcb}$
3. Pulse width limited by safe operating area

**Table 3. Thermal resistance**

| Symbol              | Parameter                        | Value | Unit               |
|---------------------|----------------------------------|-------|--------------------|
| $R_{thj-case}$      | Thermal resistance junction-case | 2.5   | $^\circ\text{C/W}$ |
| $R_{thj-pcb}^{(1)}$ | Thermal resistance junction-pcb  | 35    | $^\circ\text{C/W}$ |

1. When mounted on FR-4 board of 1inch<sup>2</sup>, 2oz Cu,  $t < 10$  sec (see [Figure 3](#))

**Table 4. Avalanche data**

| Symbol         | Parameter                                                                                            | Value | Unit |
|----------------|------------------------------------------------------------------------------------------------------|-------|------|
| $I_{AV}$       | Not-repetitive avalanche current, (pulse width limited by $T_J$ max.)                                | 7.5   | A    |
| $E_{AS}^{(1)}$ | Single pulse avalanche energy (starting $T_J = 25^\circ\text{C}$ , $I_D = I_{AV}$ , $V_{DD} = 24$ V) | 150   | mJ   |

1. Tested at wafer level only.

## 2 Electrical characteristics

( $T_{CASE} = 25\text{ °C}$  unless otherwise specified)

**Table 5. On/off states**

| Symbol        | Parameter                          | Test conditions                                              | Min. | Typ. | Max.      | Unit          |
|---------------|------------------------------------|--------------------------------------------------------------|------|------|-----------|---------------|
| $V_{(BR)DSS}$ | Drain-source breakdown voltage     | $V_{GS} = 0, I_D = 250\text{ }\mu\text{A}$                   | 40   |      |           | V             |
| $I_{DSS}$     | Zero gate voltage drain current    | $V_{GS} = 0, V_{DS} = 40\text{ V},$                          |      |      | 1         | $\mu\text{A}$ |
|               |                                    | $V_{GS} = 0, V_{DS} = 40\text{ V},$<br>$T_C = 125\text{ °C}$ |      |      | 10        | $\mu\text{A}$ |
| $I_{GSS}$     | Gate body leakage current          | $V_{DS} = 0, V_{GS} = \pm 20\text{ V}$                       |      |      | $\pm 100$ | nA            |
| $V_{GS(th)}$  | Gate threshold voltage             | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$              | 2    |      | 4         | V             |
| $R_{DS(on)}$  | Static drain-source on- resistance | $V_{GS} = 10\text{ V}, I_D = 7.5\text{ A}$                   |      | 8    | 9         | m $\Omega$    |

**Table 6. Dynamic**

| Symbol    | Parameter                    | Test conditions                                           | Min. | Typ. | Max. | Unit |
|-----------|------------------------------|-----------------------------------------------------------|------|------|------|------|
| $C_{iss}$ | Input capacitance            | $V_{GS} = 0, V_{DS} = 25\text{ V},$<br>$f = 1\text{ MHz}$ | -    | 1550 | -    | pF   |
| $C_{oss}$ | Output capacitance           |                                                           | -    | 230  | -    | pF   |
| $C_{rss}$ | Reverse transfer capacitance |                                                           | -    | 25   | -    | pF   |
| $Q_g$     | Total gate charge            | $V_{DD} = 20\text{ V}, I_D = 15\text{ A}$                 | -    | 25   | -    | nC   |
| $Q_{gs}$  | Gate-source charge           | $V_{GS} = 10\text{ V}$                                    | -    | 6    | -    | nC   |
| $Q_{gd}$  | Gate-drain charge            | (see Figure 14)                                           | -    | 5.5  | -    | nC   |

**Table 7. Switching times**

| Symbol       | Parameter           | Test conditions                                                                                                   | Min. | Typ. | Max. | Unit |
|--------------|---------------------|-------------------------------------------------------------------------------------------------------------------|------|------|------|------|
| $t_{d(on)}$  | Turn-on delay time  | $V_{DD} = 20\text{ V}, I_D = 7.5\text{ A},$<br>$R_G = 4.7\text{ }\Omega, V_{GS} = 10\text{ V}$<br>(see Figure 13) | -    | 18   | -    | ns   |
| $t_r$        | Rise time           |                                                                                                                   | -    | 45   | -    | ns   |
| $t_{d(off)}$ | Turn-off delay time |                                                                                                                   | -    | 32   | -    | ns   |
| $t_f$        | Fall time           |                                                                                                                   | -    | 5    | -    | ns   |

Table 8. Source drain diode

| Symbol          | Parameter                     | Test conditions                                                                  | Min | Typ. | Max | Unit |
|-----------------|-------------------------------|----------------------------------------------------------------------------------|-----|------|-----|------|
| $I_{SD}$        | Source-drain current          |                                                                                  | -   |      | 15  | A    |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) |                                                                                  | -   |      | 60  | A    |
| $V_{SD}^{(2)}$  | Forward on voltage            | $V_{GS} = 0$ , $I_{SD} = 15$ A                                                   | -   |      | 1.1 | V    |
| $t_{rr}$        | Reverse recovery time         | $I_{SD} = 15$ A,<br>$di/dt = 100$ A/ $\mu$ s,<br>$V_{DD} = 32$ V, $T_j = 150$ °C | -   | 30   |     | ns   |
| $Q_{rr}$        | Reverse recovery charge       |                                                                                  | -   | 35   |     | nC   |
| $I_{RRM}$       | Reverse recovery current      |                                                                                  | -   | 2.2  |     | A    |

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration = 300  $\mu$ s, duty cycle 1.5 %

## 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

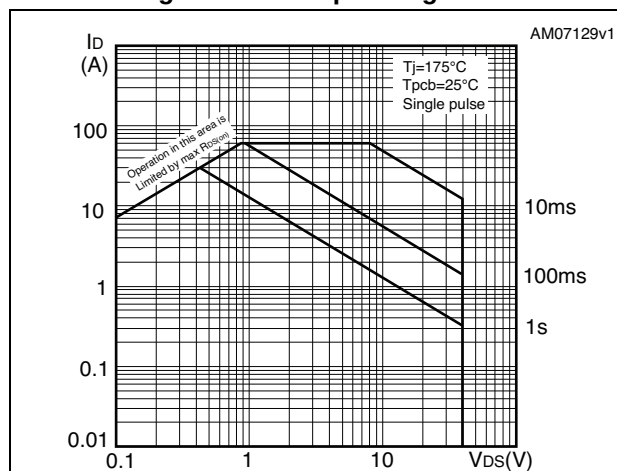


Figure 3. Thermal impedance

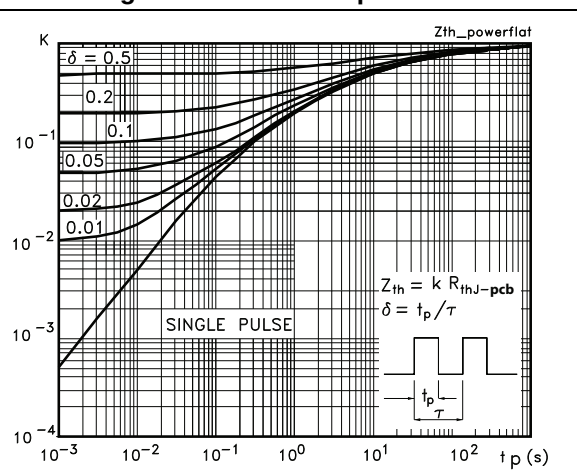


Figure 4. Output characteristics

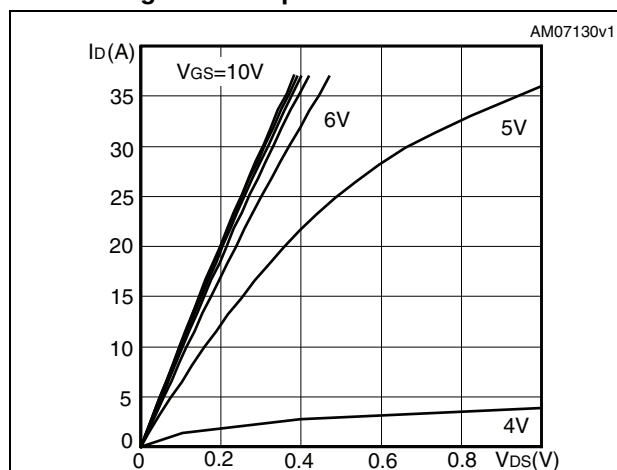


Figure 5. Transfer characteristics

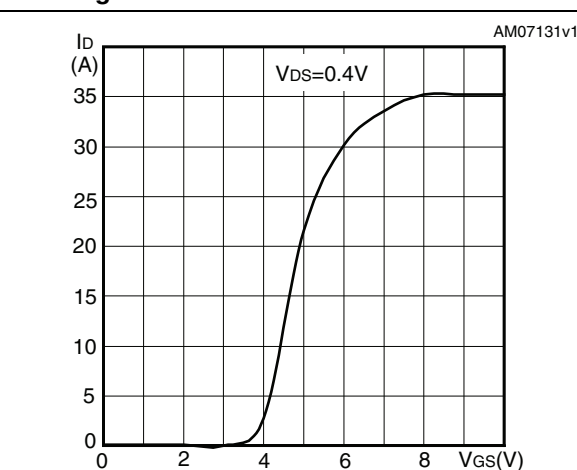
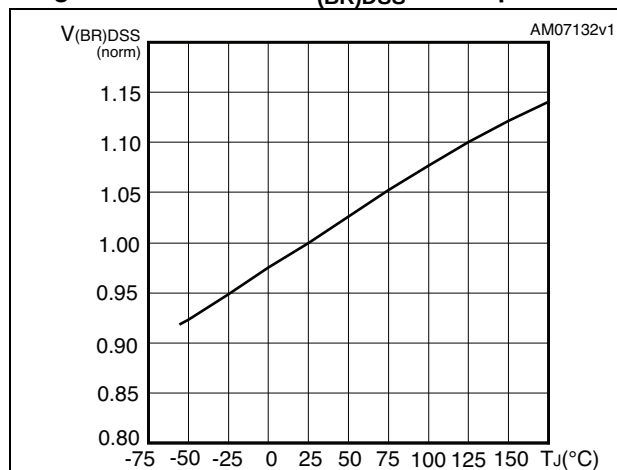
Figure 6. Normalized  $V_{(BR)DSS}$  vs temperature

Figure 7. Static drain-source on-resistance

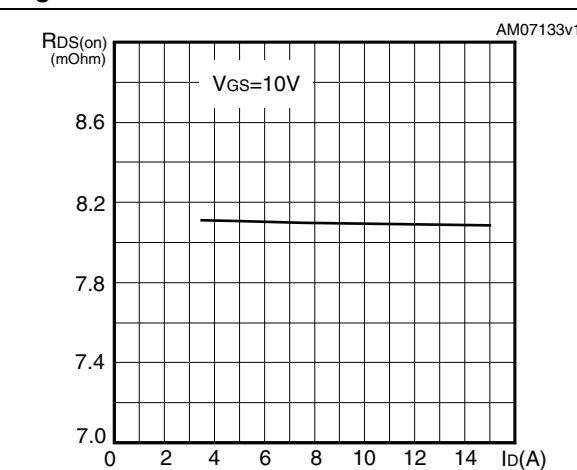


Figure 8. Gate charge vs gate-source voltage

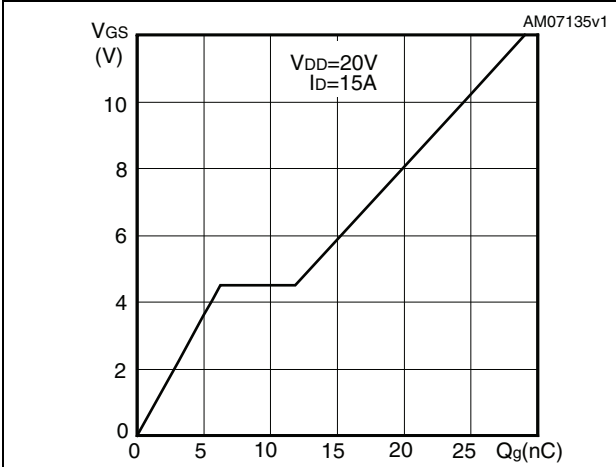


Figure 9. Capacitance variations

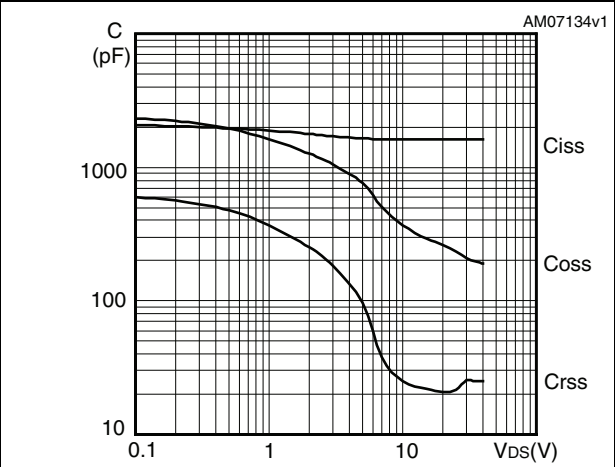


Figure 10. Normalized gate threshold voltage vs temperature

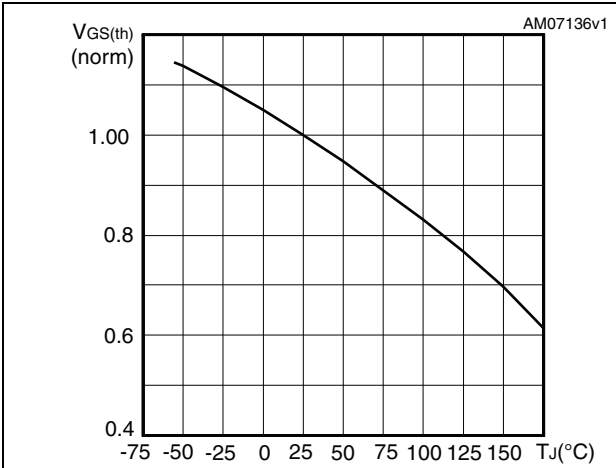


Figure 11. Normalized on-resistance vs temperature

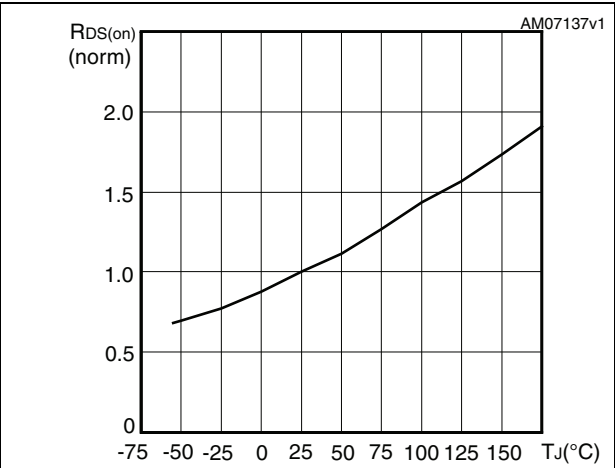
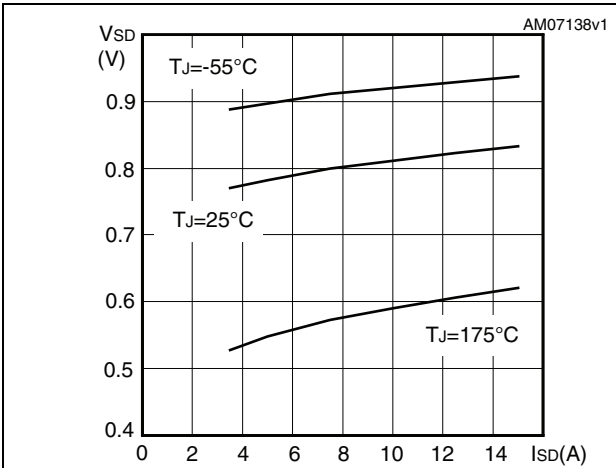


Figure 12. Source-drain diode forward characteristics



### 3 Test circuits

Figure 13. Switching times test circuit for resistive load

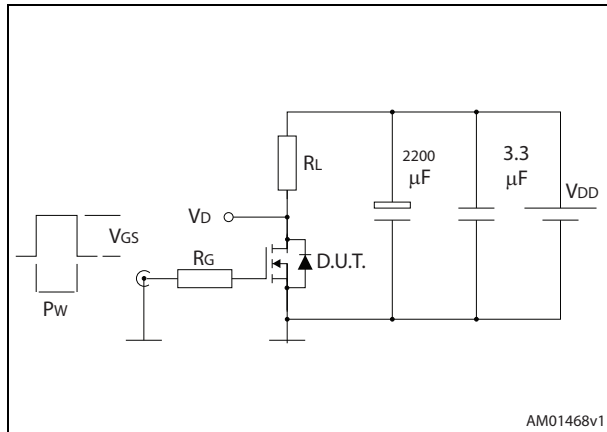


Figure 14. Gate charge test circuit

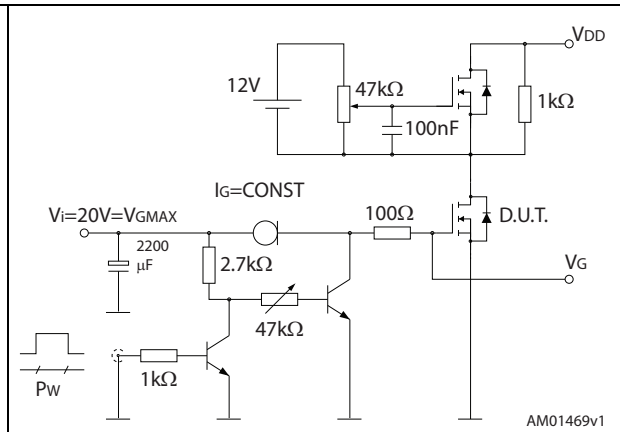


Figure 15. Test circuit for inductive load switching and diode recovery times

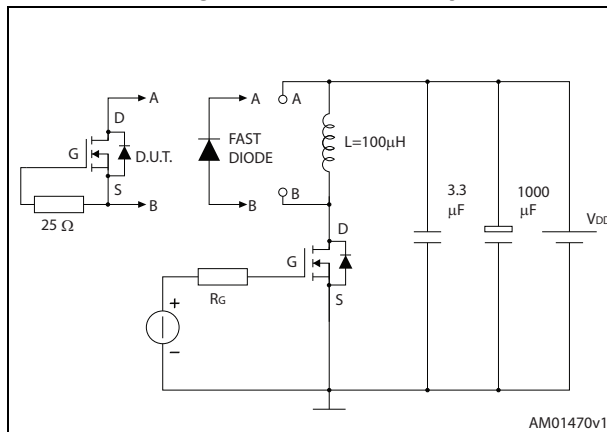


Figure 16. Unclamped inductive load test circuit

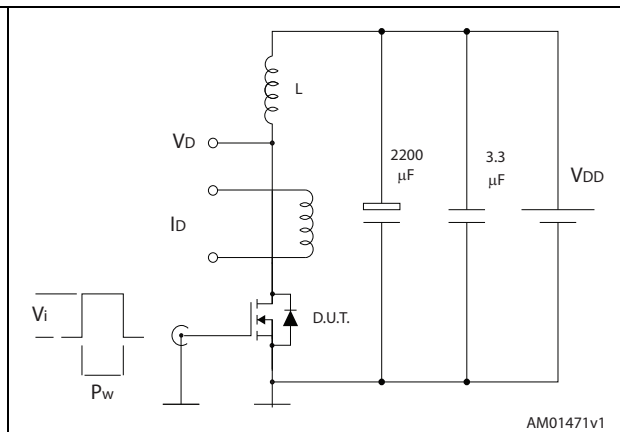


Figure 17. Unclamped inductive waveform

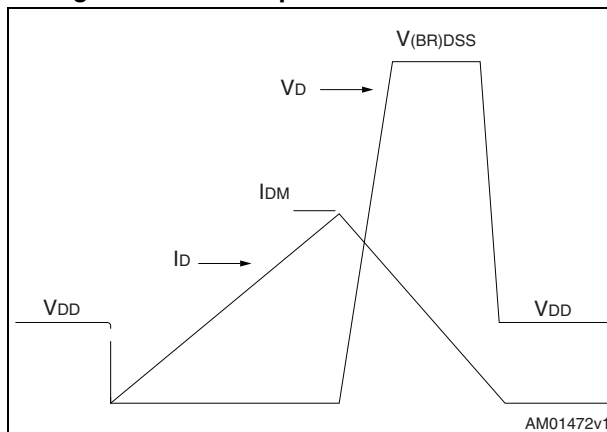
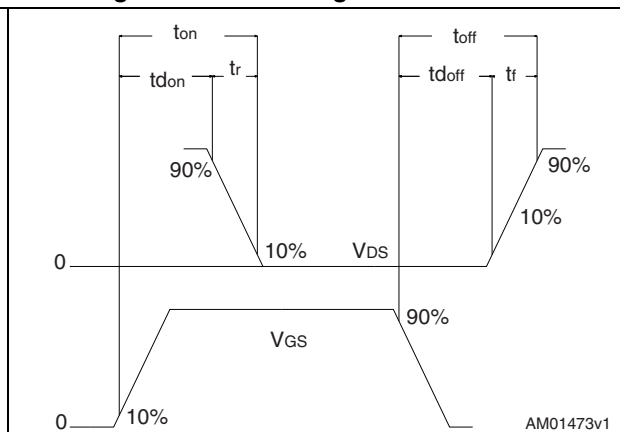


Figure 18. Switching time waveform



## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK<sup>®</sup> is an ST trademark.

Figure 19. PowerFLAT™ 5x6 double island type C outline

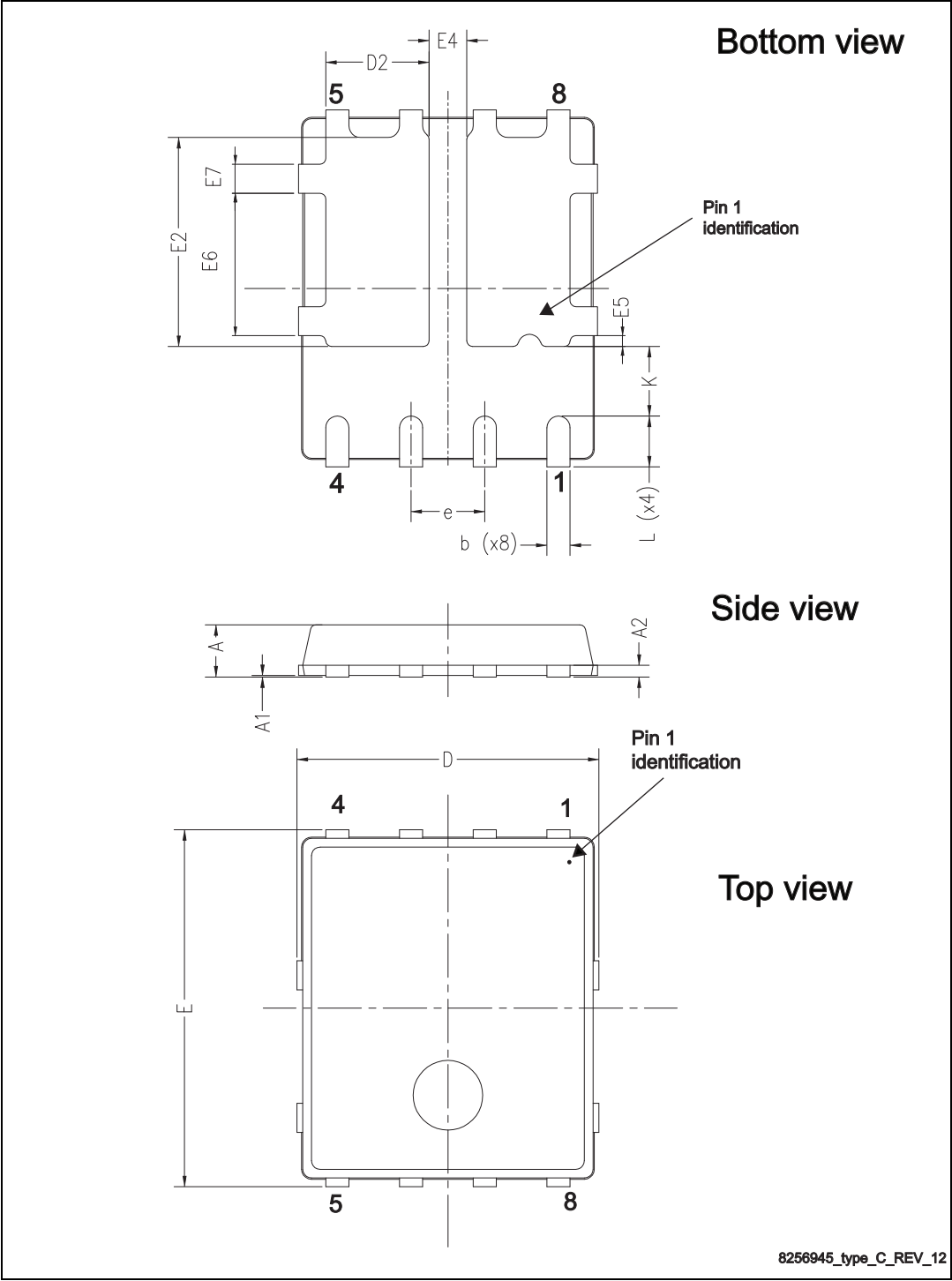


Table 9. PowerFLAT™ 5x6 double island type C mechanical data

| Dim | mm    |      |       |
|-----|-------|------|-------|
|     | Min.  | Typ. | Max   |
| A   | 0.80  |      | 1.00  |
| A1  | 0.02  |      | 0.05  |
| A2  |       | 0.25 |       |
| b   | 0.30  |      | 0.50  |
| D   |       | 5.20 |       |
| D2  | 1.68  |      | 1.88  |
| E   |       | 6.15 |       |
| e   |       | 1.27 |       |
| E2  | 3.50  |      | 3.70  |
| E4  | 0.55  |      | 0.75  |
| E5  | 0.08  |      | 0.28  |
| E6  | 2.35  |      | 2.55  |
| E7  | 0.40  |      | 0.60  |
| K   | 1.05  |      | 1.35  |
| L   | 0.725 |      | 1.025 |

Figure 20. PowerFLAT 5x6 double island WF type C outline

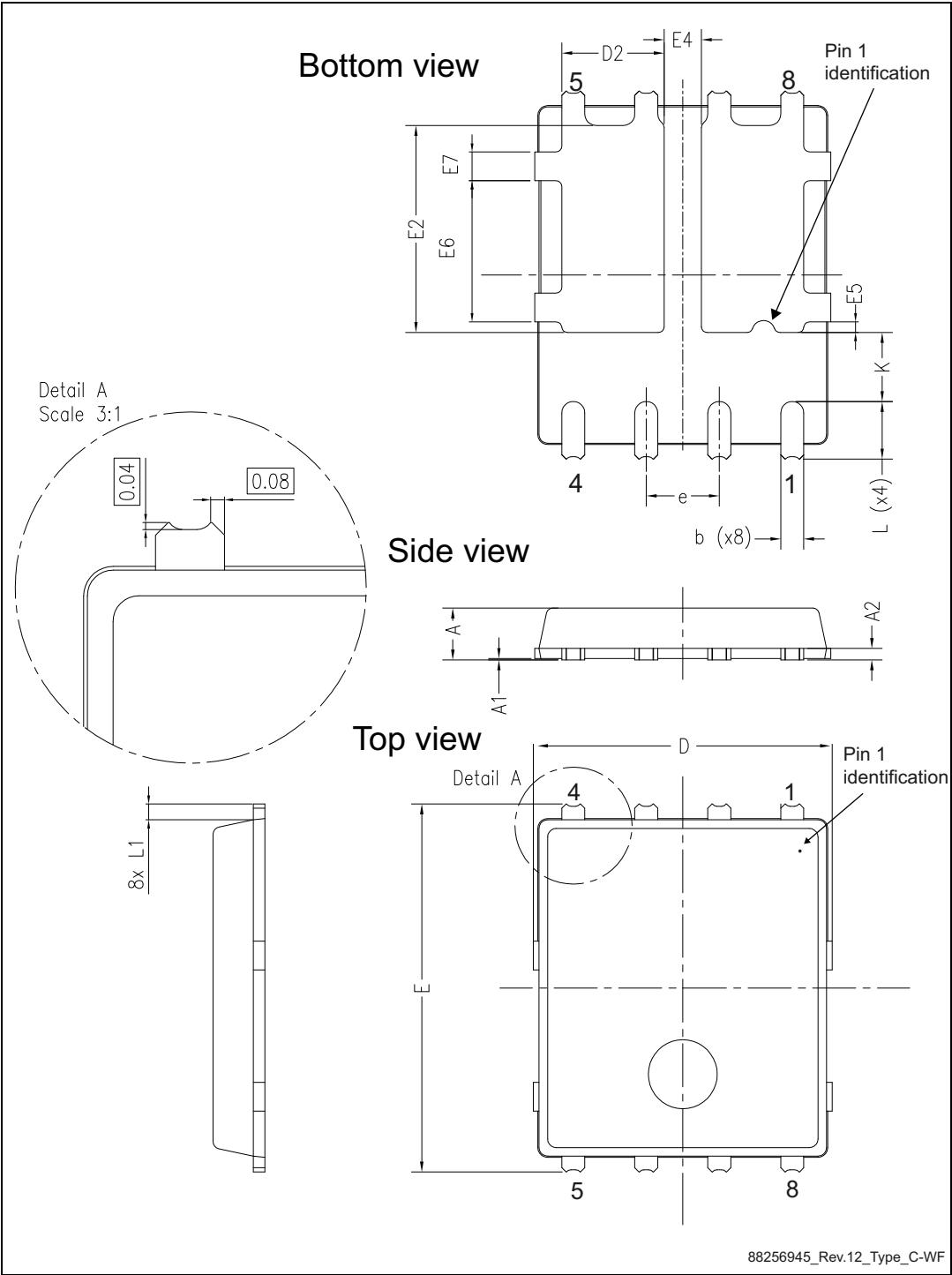
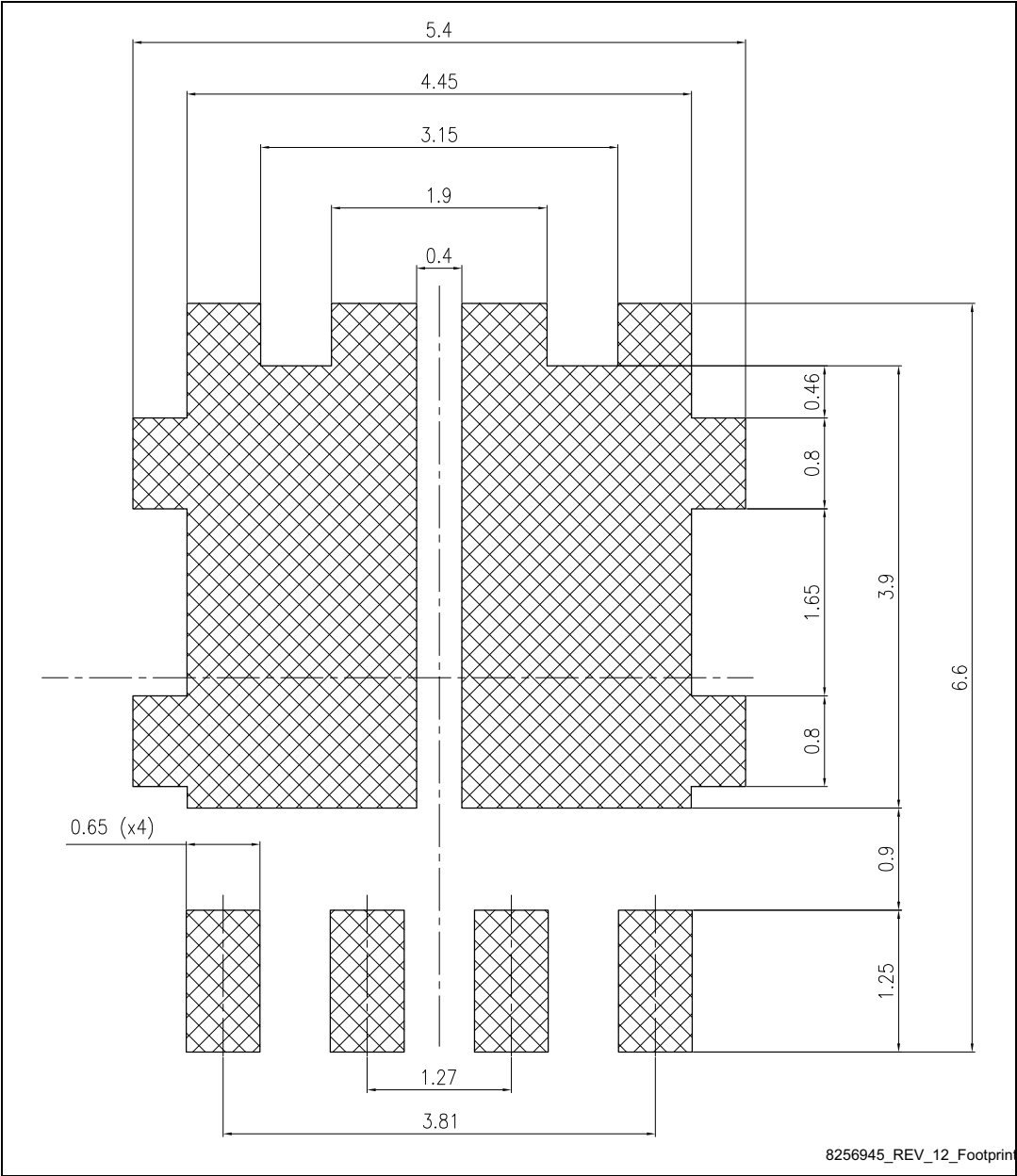


Table 10. PowerFLAT 5x6 double island WF type C mechanical data

| Ref. | Dimensions (mm) |       |      |
|------|-----------------|-------|------|
|      | Min.            | Typ.  | Max. |
| A    | 0.80            |       | 1.00 |
| A1   | 0.02            |       | 0.05 |
| A2   |                 | 0.25  |      |
| b    | 0.30            |       | 0.50 |
| D    | 5.00            | 5.20  | 5.40 |
| D2   | 1.68            |       | 1.88 |
| E    | 6.20            | 6.40  | 6.60 |
| E2   | 3.50            |       | 3.70 |
| E4   | 0.55            |       | 0.75 |
| E5   | 0.08            |       | 0.28 |
| E6   | 2.35            |       | 2.55 |
| E7   | 0.40            |       | 0.60 |
| e    |                 | 1.27  |      |
| L    | 0.90            |       | 1.10 |
| L1   |                 | 0.275 |      |
| K    | 1.05            |       | 1.35 |

Figure 21. PowerFLAT™ 5x6 double island recommended footprint  
(dimensions are in mm)



## 5 Packaging information

Figure 22. PowerFLAT™ 5x6 tape<sup>(a)</sup>

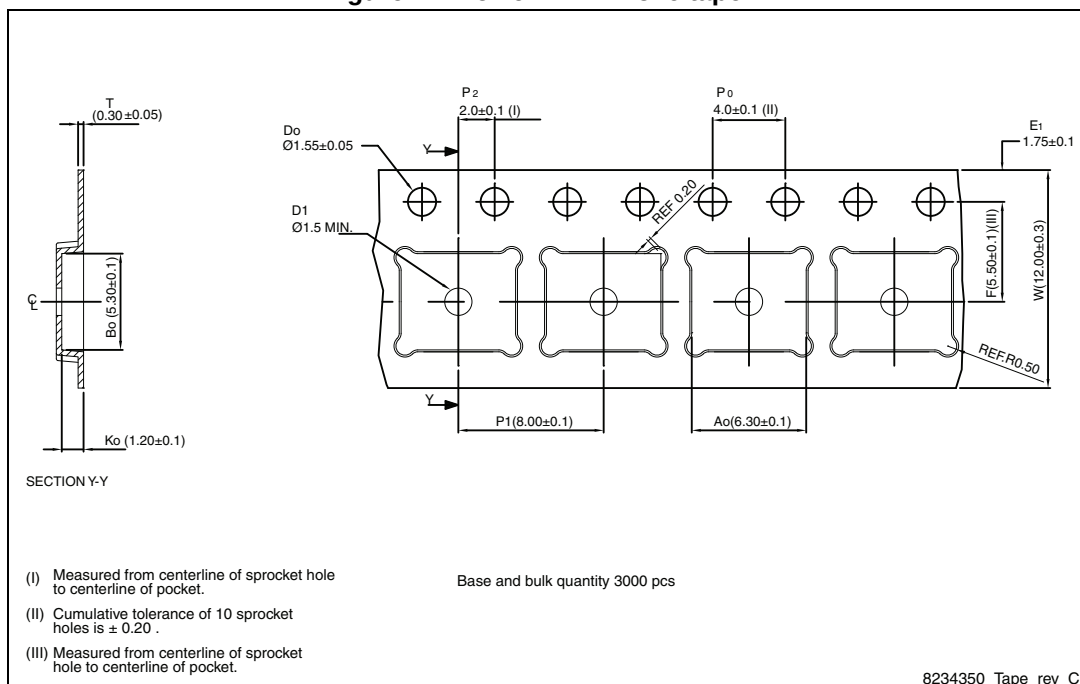
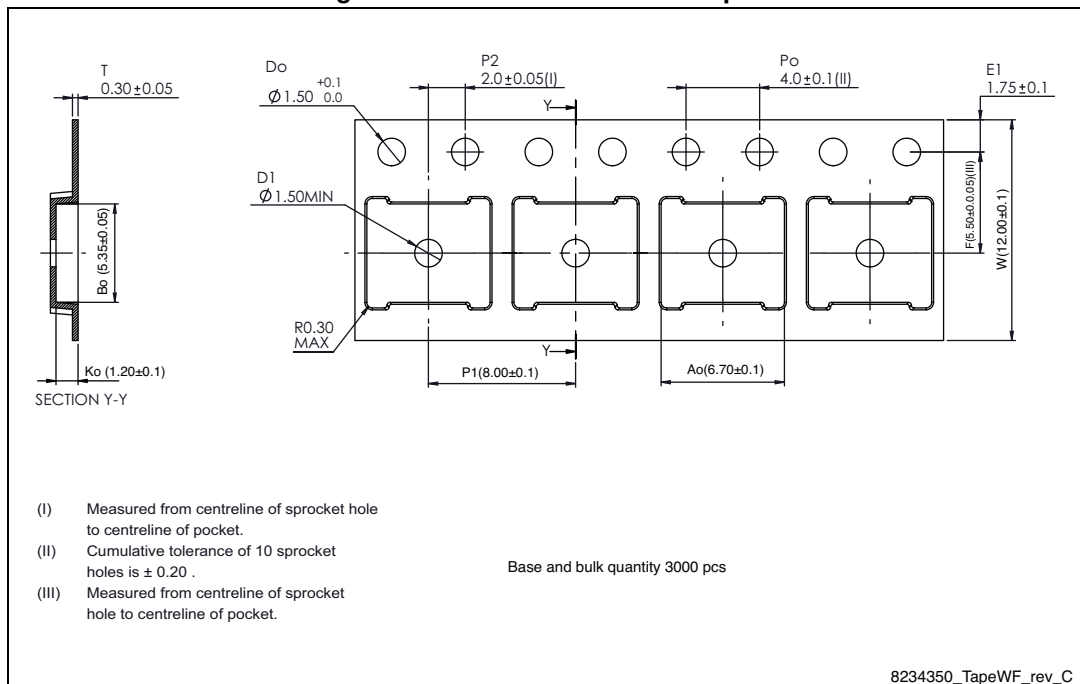


Figure 23. PowerFLAT 5x6 WF tape<sup>(a)</sup>



a. All dimensions are in millimeters.

Pin 1 identification

The diagram shows a 4-pin connector with four pins labeled ST. An arrow points to the top-left pin, which is labeled 'Pin 1 identification'.

[illegible]

## 6 Revision history

**Table 11. Document revision history**

| Date        | Revision | Changes                                                                                                                  |
|-------------|----------|--------------------------------------------------------------------------------------------------------------------------|
| 02-Sep-2010 | 1        | First release                                                                                                            |
| 01-Jul-2014 | 2        | – Updated: <a href="#">Section 4: Package information</a><br>– Minor text changes                                        |
| 13-Feb-2015 | 3        | – Updated <a href="#">Section 4: Package information</a> .<br>– Added <a href="#">Section 5: Packaging information</a> . |

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